



**SPECIFICATIONS**

1. General Information
  - . Contact Principle: Friction Technology
  - . Mounting Type: SMT
  - . Material:
    - Data Contact: Phosphor Bronze
    - Insulator: Thermoplastic, UL94 V-0
  - . Plating:
    - Gold Plating On Contact Area
    - Tin Plating On Solder Tails
2. Electrical Specification
  - . Contact Resistance: 50 Milliohms Max.
  - . Insulation Resistance: 1000 Megohms Min.
  - . Dielectric Withstanding Voltage: 500V AC R.M.S. For 1 Minute
  - . Current Rating: 0.5A Max.
3. Mechanical Specification
  - . Contact Force: 0.2N ~ 0.6N Per Pin
  - . Contact Retention Force: 0.3kgf. Min. Per Pin
  - . Durability: 5000 Cycles
4. Environment Specification
  - . Operation Temperature: -25°C ~ +85°C
  - . Humidity: 20% ~ 95%
  - . Resistance To Soldering Heat
    - Manual Soldering: 360°C, 3 Sec. Max.
    - Vapor Phase: 215°C, 30 Sec. Max.
    - IR Reflow: 260°C, 15 Sec. Max.
  - . RoHS Compliant

(.XX±0.05)  
REFERENCE PCB LAYOUT

RoHS Compliant		<b>玄茂科技股份有限公司</b> <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准 HELEN	SCALE 比例 参考	TOLERANCE .X ±0.38 .XX ±0.25 ANG. ±1°	PART NAME 品名 SIM CARD BLOCK TYPE HINGED COVER 6P H:2.5mm SMT 90° WITH LOCATING PEG, WITHOUT SWITCH ROW P=25.22 BLACK INSULATOR ROHS
DWG. 製圖 ABBY	UNIT 單位 MM	SIZE 紙張尺寸 A 4	PART NO. 料號 C0612-06DBXB00R
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